



- Glass passivated chip junction
- Thin single in-line package
- High surge current capability
- Solder dip 275 °C max. 7 s, per JESD 22-B106

- : PB
Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- : Tin plated leads, solderable per J-STD-002 and JESD22-B102
- As marked on body

($T_a=25$ Unless otherwise specified)

Device marking code				YG50DD60	YG50DD80	YG50DD100	YG50DD120
Maximum Repetitive Peak Reverse Voltage		VRRM	V	600	800	1000	1200
Maximum RMS Voltage		VRMS	V	420	560	700	840
Maximum DC blocking Voltage		VDC	V	600	800	1000	1200
Average rectified output current @60Hz sine wave, R-load	With heatsink Tc =100	Io	A	50*2			
	Without heatsink Ta =25			15*2			
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave,1 cycle, Tj=25		IFSM	A	600			
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, Tj=25				1200			

Junction temperature	T_j		-55 ~ +150			
Dielectric strength @ Terminals to case, AC 1 minute	V_{dis}	KV	2.5			
Mounting torque @Recommend torque 5kg cm	Tor	kg cm	8			

$T_a=25$ Unless otherwise specified

Maximum instantaneous forward voltage drop per diode	V_F	V	$I_{FM}=25.0A$	1.05		
Maximum DC reverse current at rated DC blocking voltage per diode	I_R	μA	$T_j=25$	5		
			$T_j=125$	500		
Typical junction capacitance	C_j	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C	292		



■ Ta=25 Unless otherwise specified							
Thermal Resistance	Between junction and ambient, Without heatsink	R _M	MRS				



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A	29.7	30.3
B	19.7	20.3
C	17.0	18.0
D	4.8	5.8
E	3.8	4.2
F	7.3	7.7
G	9.8	10.2
H	0.9	1.1
I	2.0	2.4



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